



SUPER BARRIER RECTIFIER

1A SBR®

### **Product Summary**

V <sub>RRM</sub> (V)	I <sub>0</sub> (A)	V <sub>F(MAX)</sub> (V)@ +25°C	I <sub>R(MAX)</sub> (mA) +25°C
40	1	0.51	0.5

## **Description and Applications**

The 1N5819HW1 is a single rectifier packaged in SOD123F. Offering low V<sub>F</sub> and excellent high temperature stability this device is ideal for use in general rectification applications as a:

Top View

- Boost Diode
- Blocking Diode

### **Features and Benefits**

- Low forward voltage (V<sub>F</sub>) minimizes conduction losses and improving efficiency
- Reduced high temperature reverse leakage; Increased reliability against thermal runaway failure in high temperature operation
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Mechanical Data**

- Case: SOD123F
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: Cathode Band
- Weight: 0.0016 grams (Approximate)

SOD123F



Bottom View

#### Ordering Information (Note 4)

Part Number	Case	Packaging
1N5819HW1-7-F	SOD123F	3000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

 See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

#### **Marking Information**



SL = Product Type Marking Code YM = Date Code Marking

Y = Year (ex.: C = 2015)M = Month (ex: 9 = September)

Date Code Key

Year		2013	2014	20	015	2016	201	7	2018	2019	)	2020
Code		А	В		С	D	E		F	G		Н
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	40	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Average Rectified Output Current	lo	1	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	30	А

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 5)	R <sub>0JA</sub>	135	°C/W
Typical Thermal Resistance, Junction to Case (Note 5)	R <sub>eJC</sub>	20	°C/W
Typical Thermal Resistance, Junction to Ambient (Note 6)	R <sub>0JA</sub>	75	°C/W
Typical Thermal Resistance, Junction to Case (Note 6)	R <sub>eJC</sub>	12	°C/W
Operating Junction Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

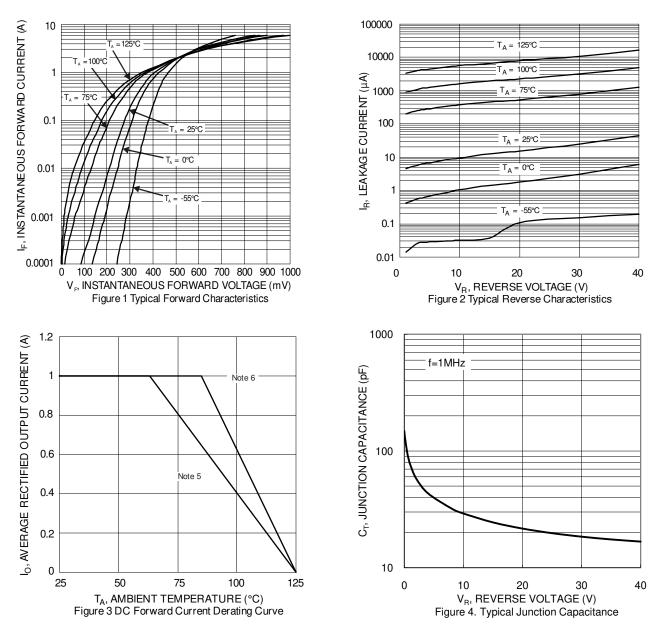
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	40	—	—	V	I <sub>R</sub> = 1.0mA
Forward Voltage Drop	VF		 0.44 0.36 0.64 0.63	0.35 0.51 — 0.75 —	V	$\begin{split} I_F &= 0.1A, \ T_J = +25^\circ C \\ I_F &= 1A, \ T_J = +25^\circ C \\ I_F &= 1A, \ T_J = +125^\circ C \\ I_F &= 3A, \ T_J = +25^\circ C \\ I_F &= 3A, \ T_J = +125^\circ C \end{split}$
Leakage Current (Note 7)	I <sub>R</sub>		0.008 0.010 0.050 —	 0.075 0.5 50	mA	
Reverse Recovery Time	t <sub>RR</sub>	_	15	—	ns	$I_F = 10mA$ , $I_{RRM} = 0.1I_R$ , $T_A = +25^{\circ}C$
Total Capacitance	Ст	_	30		pF	$V_{B} = 10V, f = 1MHz$

Notes: 5. Device mounted on 1 x MRP FR-4 PC board, 2oz.

Device mounted on 1 x with 111 41 0 board, 202.
Device mounted on 1 inch sq. copper pad, 20z.
Short duration pulse test used to minimize self-heating effect.

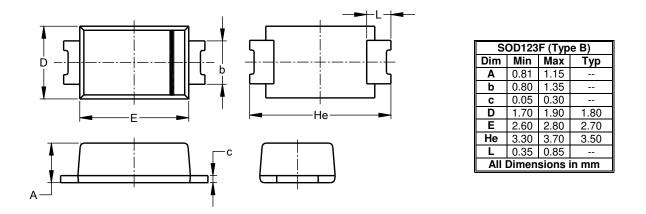






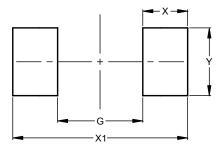
## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value			
2	(in mm)			
G	1.90			
Х	1.00			
X1	3.90			
Y	1.50			



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